

Product Disassembly Instructions

Product Category: Panel PC

Product Marketing Name / Model: SPC-221 / SPC-221-633AE/

Purpose: The document provides the basic instructions for the disassembly of products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC and 2012/19/EU, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

Item Description	Notes	BOM Detail	Quantity of items included in product
		TCB215POH0-EH8010	
		(Touch Control Board)	
	With a surface greater than 10 sq. cm	98935272200	
Printed Circuit Boards (PCB) or	Mother board, Card Reader board,	(I3 M/B)	4
Printed Circuit Assemblies (PCA)	USB Daughter board, LID Daughter	9893PW0801E	
	board	(Power Board)	
		9693PH2302E	
		(PH-23)	
Batteries	All types including standard alkaline	1760000897-11	
	and lithium coin or button style	(BATTERY 3V/200	4
	batteries 6cell battery or 9 cell	mAh W/CABLE	1
	battery, and RTC battery	BR2032 W/C)	
External electrical cables and Power cord		N/A	0
Liquid Crystal Displays (LCD) with	Includes background illuminated	96LEDK-A215FH30NF2	
a surface greater than 100 sq cm	displays with gas discharge lamps	1	
Cathode Ray Tubes (CRT)		N/A	0
Gas Discharge Lamps		N/A	0



Electrolytic Capacitors /	N/A	
Condensers measuring greater		0
than 2.5 cm in diameter or height		

Item Description	Notes	Quantity of items included in product
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Capacitors / condensers (Containing PCB)		0
Plastics containing Brominated Flame Retardants weighing > 25 grams	(Not including PCBs or PCAs already listed as a separate item above)	0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Asbestos waste and components which contain asbestos		0
Components containing refractory ceramic fibers		0
Chlorofluorocarbons (CFC), hydrochlorofluorocarbons (HCFC) or hydrofluorocarbons(HFC), hydrocarbons (HC)		0
Components, parts and materials containing radioactive substances		0



2.0 Disassembly Tool

List the tools that would typically be used to disassemble the product to a point where components and materials can be removed.

Disassembly Tool	Picture
Screwdriver	0
Lever	
Star Screwdriver	0
Hexagon Driver	0
Slanted pliers	
Pliers	
Hammer	8-
Knife	
Others	



3.0 Product Disassembly Process

- 3.1 List the basic steps that should typically be followed to remove components and materials.
- A: Disassemble Rear cover module and separate the product to 3 modules A, B, C.
- A-1. Take 10 rubber caps off back cover
- A-2. Release 10 pcs of screw from the product.
- A-3. Release 8 pcs of screw to remove back cover module.
- A-4. Release 13 pcs of screw to remove middle bracket module.
- B: Disassemble Middle Bracket Module
- B-1. Release 6 pcs of screw to remove Heat sink block.
- B-2. Release 4 pcs of screw to remove main board.
- B-3. Release 2 pcs of screw to remove Touch Screen Driving Board.
- B-4. Release 3 pcs of screw to remove power board.
- B-5. Release 2 pcs of screw to remove iKey control board.
- B-6. Release 4 pcs of screw to remove IO bracket.
- B-7. Release 4 pcs of screw to remove HDD bracket.
- C: Disassemble Panel Module
- C-1-1. Release 3 pcs of screw in right side of LCD bracket.
- C-1-2. Release 3 pcs of screw in left side of LCD bracket, then to take off LCD module from Panel module.
- C-2-1. Release 2 pcs of screw to remove right side LCD bracket.
- C-2-2. Release 2 pcs of screw to remove left side LCD bracket.
- C-3. Release 1 piece of screw to remove LED indicator board.
- D: Disassemble HDD Cover from rear cover module.
- D-1. Take 4 rubber caps off HDD cover
- D-2. Release 4 pcs of screw to remove HDD cover from rear cover module.1.
- 3.2 Exploded view drawing. Insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).





